

# SOT402-1

plastic thin shrink small outline package; 14 leads; body width 4.4 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	TSSOP14
<b>Package type industry code</b>	TSSOP14
<b>Package style descriptive code</b>	TSSOP (thin shrink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-153
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-2-2003

Table 1. Package summary

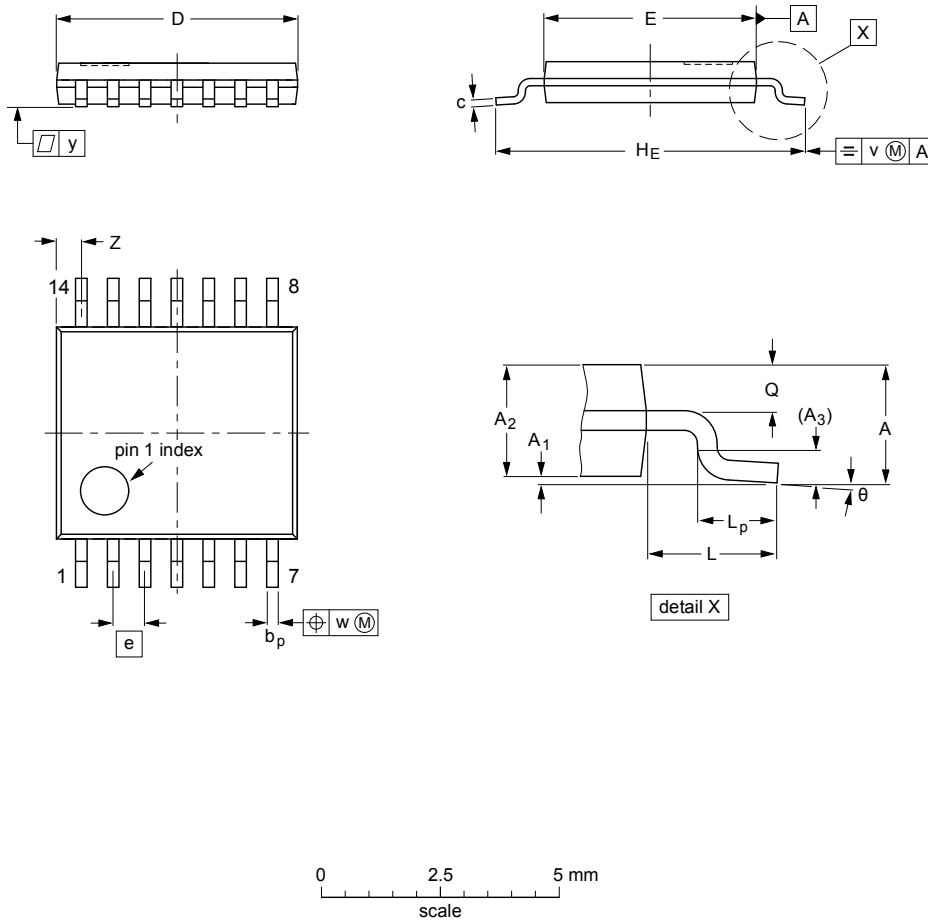
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A <sub>2</sub>	package height	0.8	-	0.9	0.95	mm
n <sub>2</sub>	actual quantity of termination	-	-	14	-	



2. Package outline

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

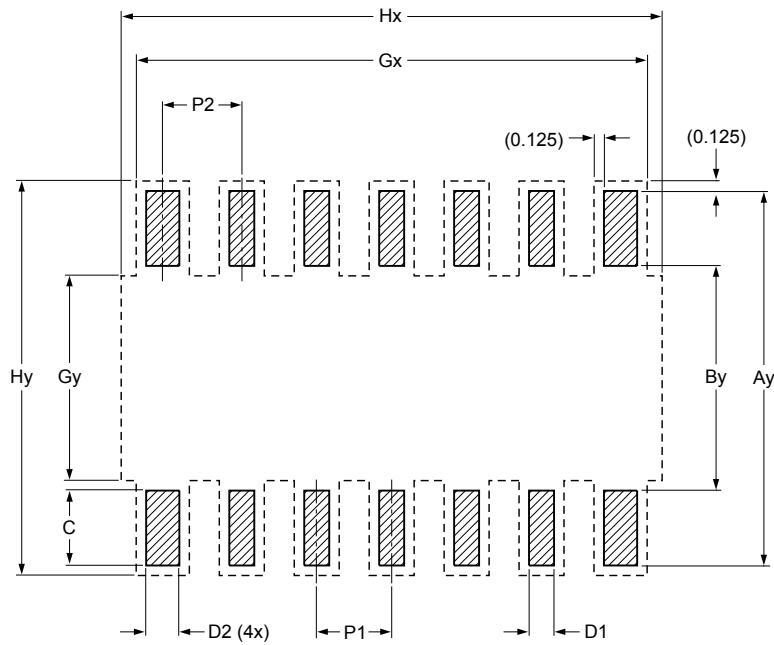
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				99-12-27 03-02-18

Fig. 1. Package outline TSSOP14 (SOT402-1)


### 3. Soldering

Footprint information for reflow soldering of TSSOP14 package

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Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
 - - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	4.950	5.300	5.800	7.450

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Fig. 2. Reflow soldering footprint for TSSOP14 (SOT402-1)

plastic thin shrink small outline package; 14 leads; body width 4.4 mm

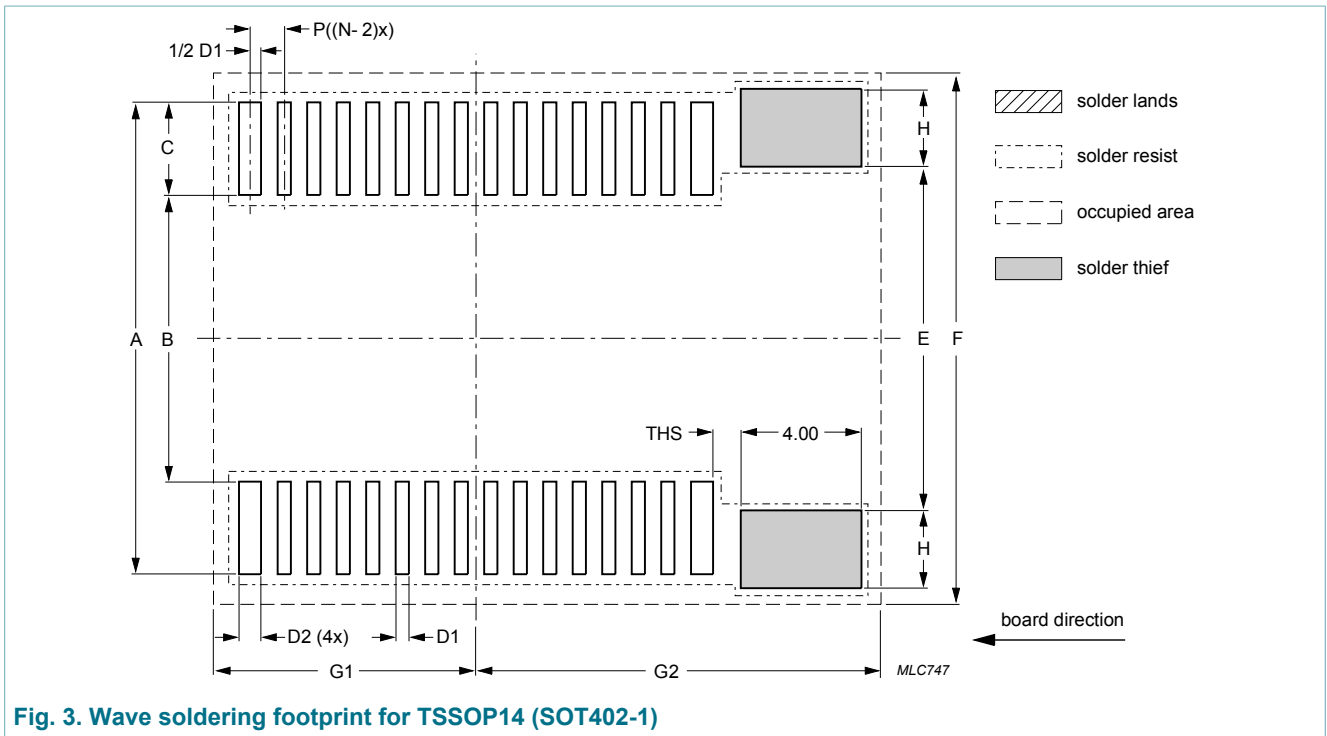


Fig. 3. Wave soldering footprint for TSSOP14 (SOT402-1)

## 4. Legal information

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